



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-07-26
<b>Contact Name *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Authorized Representative *</b>	Rossana Bonaccorso
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T3035H-8G	7BD1*308SAM1	A	3068	2018-07-26
Amount	UoM	Unit type	ST ECOPACK Grade	
1600	mg	Each	ECOPACK2	
Comment		ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-10.5-1.27	3	gull wing	
Comment	D2PAK CLIP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
7c-l	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : ELV directive : 2000/53/EC amended 2016/774 _May 2016	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
10a	Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound. This exemption does not cover the use of lead in: — glass in bulbs and glaze of spark plugs, — dielectric ceramic materials of components listed under 10(b), 10(c) and 10(d)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.67	Die	416
Lead	57.86	Die - Soft solder	36162
Lead-Borate Glass	3.09	Die	1930

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	57.86	Die - Soft solder	36162
Lead borate glass	1000 ppm	3.088	Die	1930
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	57.86	Die - Soft solder	1633941
Lead borate glass	1000 ppm	3.088	Die	49134

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	78D1*308SAM1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	62.848	mg	supplier	die	Silicon (Si)	7440-21-3		14.087	mg	224156	8805
				supplier	metallization	Gold (Au)	7440-57-5		0.054	mg	859	34
				supplier	metallization	Nickel (Ni)	7440-02-0		0.283	mg	4503	177
				JIG - R	Passivation	Lead (Pb)	7439-92-1	7c-I-Electrical and e	44.855	mg	713695	28034
				supplier	Passivation	Silicon Oxide	7631-86-9		0.080	mg	1273	50
				supplier	back side metallization	Gold (Au)	7440-57-5		0.018	mg	286	11
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.383	mg	6094	239
				JIG - R & California 65	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	3.088	mg	49134	1930
				supplier	alloy	Copper (Cu)	7440-50-8		699.838	mg	998700	437399
				supplier	alloy	Iron (Fe)	7439-89-6		0.701	mg	1000	438
Leadframe	M-004 Copper and its alloys	700.749	mg	supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.210	mg	300	131
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	13.004	mg	920246	8128
				supplier	solder	Silver (Ag)	7440-22-4		0.352	mg	24910	220
				supplier	solder	Tin (Sn)	7440-31-5		0.704	mg	49820	440
Soft solder	Solder	14.131	mg	JIG - R	solder	flux residue	Proprietary		0.071	mg	5024	44
				supplier	solder	flux residue	Proprietary		0.071	mg	5024	44
				supplier	solder	flux residue	Proprietary		0.071	mg	5024	44
				supplier	solder	flux residue	Proprietary		0.071	mg	5024	44
				supplier	solder	flux residue	Proprietary		0.071	mg	5024	44
Encapsulation	M-011 Other inorganic materials	784.333	mg	supplier	mold compound	Silica, vitreous	60676-86-0		596.092	mg	759999	372558
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		80.002	mg	102000	50001
				supplier	mold compound	Phenol resin	9003-35-4		47.060	mg	60000	29413
				supplier	mold compound	Others	Proprietary		39.217	mg	50000	24511
				supplier	mold compound	Metal hydroxide	21645-51-2		15.687	mg	20000	9804
				supplier	mold compound	Carbon black	1333-86-4		6.275	mg	8001	3921
				supplier	mold compound	Carbon black	1333-86-4		6.275	mg	8001	3921
Connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	3946
Clip	M-004 Copper and its alloys	31.625	mg	supplier	alloy	Copper ( Cu)	7440-50-8		31.625	mg	1000000	19766